

Title (en)

Semiconductor wafer polishing apparatus and polishing method

Title (de)

Halbleiterscheibepoliervorrichtung und Polierverfahren

Title (fr)

Dispositif de polissage de plaquette semiconductrice et procédé de polissage

Publication

EP 1291132 A3 20040331 (EN)

Application

EP 02019759 A 20020904

Priority

JP 2001269640 A 20010906

Abstract (en)

[origin: EP1291132A2] An object of the present invention is to unchange the order of wafers when passed through a wafer outer peripheral part polishing apparatus, thereby simplifying control for each wafer. In predetermined positions of a frame of a wafer outer peripheral part polishing unit, there are arranged and attached a wafer cassette reception and discharge opening unit, a wafer position aligning unit, a wafer notch polishing unit, a wafer circumferential part polishing unit, an inside carrier unit, a first slurry supply device, and a second slurry supply device. The inside carrier unit has a first carrier sub-unit, a second carrier sub-unit, and a third carrier sub-unit. After a wafer taken out from the wafer cassette reception and discharge opening unit is polished, the wafer is returned to the same slot of the same cassette from which it is taken out. Thus, the order is not changed. <IMAGE>

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B24B 41/00; **B24B 9/06**

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CPC (source: EP)

B24B 9/065 (2013.01); **B24B 41/005** (2013.01)

Citation (search report)

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- [Y] EP 1120191 A2 20010801 - TSK AMERICA INC [US]
- [YA] US 5769695 A 19980623 - KATAYAMA ICHIRO [JP]
- [Y] PATENT ABSTRACTS OF JAPAN vol. 2000, no. 07 29 September 2000 (2000-09-29)

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CN109605207A; EP1872394A4; US10910256B2; TWI462169B

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